

ABSTRACT

To provide a method of producing an encapsulating molding material tablet by which adhesion of an encapsulating molding material to the punch surface of a tablet forming machine can be reduced, an encapsulating molding material tablet produced by this method, and an electronic part apparatus equipped with an element encapsulated using this encapsulating molding material tablet. A method of producing an encapsulating molding material tablet in which a release agent dissolved in a solvent is fed to the punch surface of a tablet forming machine to form a release agent layer having a thickness of over 0.001 μm and less than 0.07 μm on the above-mentioned punch surface, then, an encapsulating molding material is fed to the above-mentioned tablet forming machine for molding the material, an encapsulating molding material tablet produced by this method or having a contact angle ratio of 1.15 or more and less than 1.35, and an electron part apparatus equipped with an element encapsulated using this encapsulating molding material tablet.



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